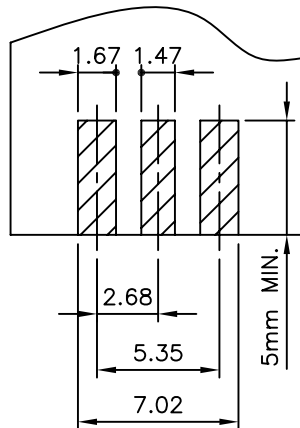
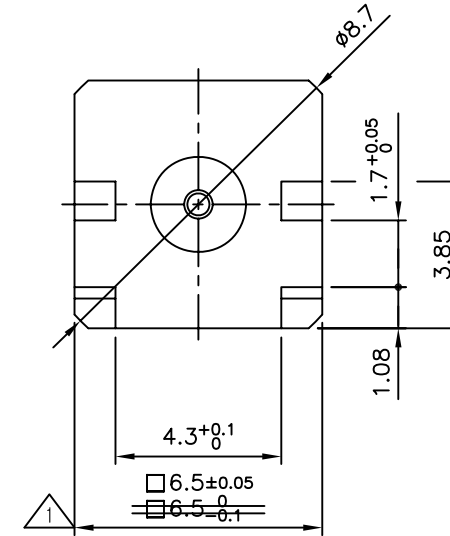
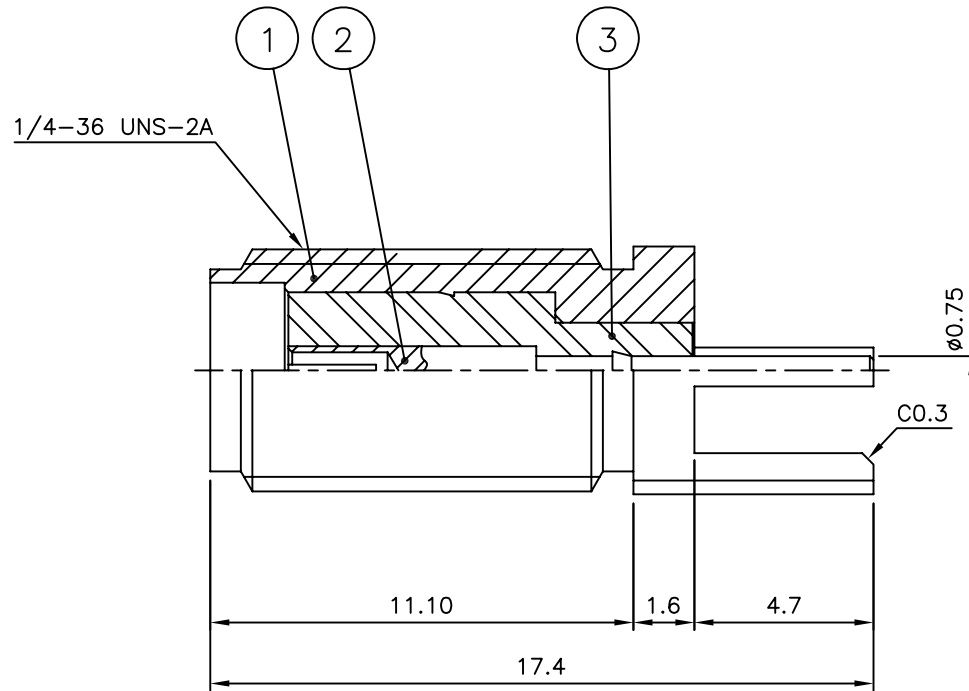


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	I.C.KIM		2017.04.25.
1	[설변No.201705-0006] 원제품 과 BODY 치수공차 상이함으로 인한 공차 변경	S.Y.EUN	I.C.KIM	2017.05.22.



LANDING PAD DIMENSIONS

3	INSULATOR	1	TEFLON		DIN02001-N/1
2	CONTACT	1	BeCu	Gold Plate	DCT02584-5/1
1	BODY	1	MBsBD	Gold Plate	DBD03045-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2017. 05. 22.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY		KJ COMTECH CO.,LTD. TITLE SMA50 PCB JS-4R Edge
		DRAWN BY	S.Y.EUN	
FINISH		SCALE	UNIT	A4 DWG NO. CN02791-7/2 REVISION 1 SHEET 1 of 1
		5/1	mm	